

# NCE N-Channel Enhancement Mode Power MOSFET



The NCE40H21CD uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

## **General Features**

- V<sub>DS</sub> =40V ,I<sub>D</sub> =210A
  R<sub>DS(ON)</sub> < 2.5mΩ @ V<sub>GS</sub>=10V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E<sub>AS</sub>
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

#### Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED!

#### 100% ΔVds TESTED!

## Package Marking and Ordering Information

| Device Marking | Device     | Device Package | Reel Size | Tape width | Quantity |
|----------------|------------|----------------|-----------|------------|----------|
| NCE40H21CD     | NCE40H21CD | TO-263-2L      | -         | -          | -        |

## Absolute Maximum Ratings (T<sub>A</sub>=25℃ unless otherwise noted)

| Parameter  | Symbol                           | Limit      | Unit |
|--|----------------------------------|------------|------|
| Drain-Source Voltage                             | VDS                              | 40         | V    |
| Gate-Source Voltage                              | Vgs                              | ±20        | V    |
| Drain Current-Continuous                         | I <sub>D</sub>                   | 210        | А    |
| Drain Current-Continuous(Tc=100℃)                | I <sub>D</sub> (100℃)            | 148        | А    |
| Pulsed Drain Current                             | I <sub>DM</sub>                  | 840        | А    |
| Maximum Power Dissipation                        | PD                               | 310        | W    |
| Derating factor                                  |                                  | 2.07       | W/℃  |
| Single pulse avalanche energy (Note 5)           | E <sub>AS</sub>                  | 1800       | mJ   |
| Operating Junction and Storage Temperature Range | T <sub>J</sub> ,T <sub>STG</sub> | -55 To 175 | °C   |



(2) D







## **Thermal Characteristic**

| Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup> | R <sub>θJC</sub> | 0.48 | °C/W |
|--|------------------|------|------|
|--|------------------|------|------|

## Electrical Characteristics (T<sub>A</sub>=25<sup>°</sup>C unless otherwise noted)

| Parameter                          | Symbol              | Condition  | Min | Тур  | Max  | Unit |
|------------------------------------|---------------------|--|-----|------|------|------|
| Off Characteristics                |                     |  |     | •    |      |      |
| Drain-Source Breakdown Voltage     | BV <sub>DSS</sub>   | V <sub>GS</sub> =0V I <sub>D</sub> =250µA 40                         |     |      | -    | V    |
| Zero Gate Voltage Drain Current    | I <sub>DSS</sub>    | V <sub>DS</sub> =40V,V <sub>GS</sub> =0V                             | -   | -    | 1    | μA   |
| Gate-Body Leakage Current          | I <sub>GSS</sub>    | V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V                            | -   | -    | ±100 | nA   |
| On Characteristics (Note 3)        |                     |  |     | •    |      |      |
| Gate Threshold Voltage             | V <sub>GS(th)</sub> | V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA              | 2   | 3    | 4    | V    |
| Drain-Source On-State Resistance   | R <sub>DS(ON)</sub> | V <sub>GS</sub> =10V, I <sub>D</sub> =40A                            | -   | 1.8  | 2.5  | mΩ   |
| Forward Transconductance           | <b>g</b> fs         | V <sub>DS</sub> =24V,I <sub>D</sub> =40A                             | 160 | -    | -    | S    |
| Dynamic Characteristics (Note4)    |                     |  |     |      |      |      |
| Input Capacitance                  | Clss                |  | -   | 7800 | -    | PF   |
| Output Capacitance                 | C <sub>oss</sub>    | V <sub>DS</sub> =25V,V <sub>GS</sub> =0V,<br>F=1.0MHz                | -   | 1144 | -    | PF   |
| Reverse Transfer Capacitance       | C <sub>rss</sub>    | F=1.0WHZ   | -   | 820  | -    | PF   |
| Switching Characteristics (Note 4) |                     |  |     |      |      | L    |
| Turn-on Delay Time                 | t <sub>d(on)</sub>  |  | -   | 40   | -    | nS   |
| Turn-on Rise Time                  | tr                  | VDD=30V,ID=2A,RL=15Ω,  | -   | 38   | -    | nS   |
| Turn-Off Delay Time                | $t_{d(off)}$        | RG=2.5Ω,VGS=10V  | -   | 140  | -    | nS   |
| Turn-Off Fall Time                 | t <sub>f</sub>      |  | -   | 60   | -    | nS   |
| Total Gate Charge                  | Qg                  |  | -   | 215  | -    | nC   |
| Gate-Source Charge                 | Q <sub>gs</sub>     | ID=30A,VDD=30V,VGS=10V   | -   | 41   | -    | nC   |
| Gate-Drain Charge                  | Q <sub>gd</sub>     |  | -   | 83   | -    | nC   |
| Drain-Source Diode Characteristics |                     | I  |     |      |      | 1    |
| Diode Forward Voltage (Note 3)     | V <sub>SD</sub>     | V <sub>GS</sub> =0V,I <sub>S</sub> =40A                              | -   | 0.85 | 1.2  | V    |
| Diode Forward Current (Note 2)     | I <sub>S</sub>      |  | -   | -    | 210  | А    |
| Reverse Recovery Time              | trr                 | TJ = 25°C, IF = 40A  | -   | 47   |      | nS   |
| Reverse Recovery Charge            | Qrr                 | di/dt = 100A/µs <sup>(Note3)</sup>                                   | -   | 76   |      | nC   |
| Forward Turn-On Time               | t <sub>on</sub>     | Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD) |     |      |      |      |

#### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- **3.** Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition: Tj=25 $^\circ\! \mathbb{C}$  ,V\_DD=20V,V\_G=10V,L=1mH,Rg=25\Omega



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## Test circuit

1) E<sub>AS</sub> test Circuits



## 2) Gate charge test Circuit:



3) Switch Time Test Circuit:







200

240

280

GS = 0V

320

## **Typical Electrical and Thermal Characteristics (Curves)**









Square Wave Pluse Duration (sec) Figure 11 Normalized Maximum Transient Thermal Impedance



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# TO-263-2L Package Information



| Symbol | Dimensions | In Millimeters | Dimensions In Inches |           |  |
|--------|------------|----------------|----------------------|-----------|--|
|        | Min.       | Max.           | Min.                 | Max.      |  |
| A      | 4.470      | 4.670          | 0.176                | 0.184     |  |
| A1     | 0.000      | 0.150          | 0.000                | 0.006     |  |
| В      | 1.170      | 1.370          | 0.046                | 0.054     |  |
| b      | 0.710      | 0.910          | 0.028                | 0.036     |  |
| b1     | 1.170      | 1.370          | 0.046                | 0.054     |  |
| С      | 0.310      | 0.530          | 0.012                | 0.021     |  |
| c1     | 1.170      | 1.370          | 0.046                | 0.054     |  |
| D      | 10.010     | 10.310         | 0.394                | 0.406     |  |
| E      | 8.500      | 8.900          | 0.335                | 0.350     |  |
| e      | 2.540 TYP. |                | 0.100 TYP.           |           |  |
| e1     | 4.980      | 5.180          | 0.196                | 0.204     |  |
| L      | 15.050     | 15.450         | 0.593                | 0.608     |  |
| L1     | 5.080      | 5.480          | 0.200                | 0.216     |  |
| L2     | 2.340      | 2.740          | 0.092                | 0.108     |  |
| L3     | 1.300      | 1.700          | 0.051                | 0.067     |  |
| V      | 5.600 REF  |                | 0.220                | 0.220 REF |  |





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